

B. Claims

The following is a complete listing of the claims, and replaces all earlier versions and listings.

1. (Currently Amended) A solution comprising ionic Fe, ionic Pt, and tartaric acid as a complex agent at a molar ratio of the ionic Fe to the ionic Pt ranging from 0.75 to 3, wherein the solution is such that it is capable of depositing FePt or FePtCu a composition consisting of Fe and Pt or Fe, Pt, and Cu is deposited when plating using the solution is performed.

2. (Cancelled)

3. (Previously Presented) The solution according to claim 1, wherein the concentration of the ionic Fe ranges from 0.005 mol/L to 0.1 mol/L.

4. (Previously Presented) The solution according to claim 1, wherein the solution has a pH ranging from 5.0 to 10.5.

5. (Previously Presented) The solution according to claim 1, wherein the ionic Fe and the ionic Pt form a double complex constituted of an Fe complex and a Pt complex.

6. (Previously Presented) The solution according to claim 1, wherein the solution contains ionic Cu and a complex agent for the ionic Cu.

7. (Withdrawn) A process for producing a structure comprising steps of:

providing an electrode and an object to be plated in a vessel containing a plating solution set forth in claim 1, and
plating the object with a magnetic material containing FePt from the plating solution by applying voltage to the electrode to form a structure.

8. (Withdrawn) A process for producing a structure, wherein the structure formed in claim 7 is heat-treated further at a temperature ranging from 450°C to 750°C.

9. (Withdrawn) A process for producing a structure, wherein the structure set forth in claim 7 is heat-treated further in the presence of hydrogen.

10. (Withdrawn) The process for producing a structure according to claim 7, wherein the object to be plated is a structure having holes, and the step of plating the object to form the structure is deposition of the magnetic material containing FePt into the holes.

11. (Withdrawn) An apparatus comprising a plating solution as set forth in claim 1, a vessel for holding the plating solution, and electrodes, for conducting plating by application of a voltage to the electrodes.